

FABRICATION NOTES:

1. BASE MATERIAL:
 - A. 1.6mm +/- 10% THICK GLASS EPOXY, 170C Tg FR-4, NATURAL COLOR, NEMA GRADE
 - B. COPPER WEIGHT AS PER PROVIDED STACKUP
2. FINISH: ALL EXTERNAL METAL FINISH, NOT COVERED BY SOLDERMASK, SHALL BE ENIG
3. FINISHED SIZES:
 - A. ALL HOLE DIAMETERS ARE STATED AS FINISHED HOLE SIZES. ALL PLATED THROUGH HOLES TO HAVE A MINIMUM OF 1 mil COPPER
 - B. ALL TRACE WIDTHS ARE STATED AS FINISHED TRACE WIDTHS
4. DIMENSIONS:
 - A. ALL DIMENSIONS ARE IN mm (millimeters) UNLESS OTHERWISE STATED
 - B. CONFIGURATION OF THE PRINTED CIRCUIT BOARD NOT SPECIFICALLY DIMENSIONED ON THE DRAWING SHALL BE CONTROLLED BY THE ELECTRONIC DATA
5. SOLDERMASK:
 - A. PHOTO-IMAGED, LIQUID POLYMER AS INDICATED WITHIN THE ELECTRONIC DATA IN ACCORDANCE WITH IPC-SM840E, TYPE B1, CLASS T, OVER BARE COPPER
 - B. SOLDERMASK COLOR IS TO BE GREEN
 - C. SOLDERMASK SLIVERS OF LESS THAN 0.076MM CAN BE ELIMINATED
 - D. FINISH IS TO BE MATTE
6. SILKSCREEN:
 - A. SILKSCREEN AS INDICATED WITHIN THE ELECTRONIC DATA, USING NON-CONDUCTIVE WHITE EPOXY INK
 - B. SILKSCREEN TO BE REMOVED FROM VIAS, PADS, AND HOLES PROVIDING A MINIMUM CLEARANCE OF 0.127mm
 - C. VENDOR'S UL LOGO OR DESIGNATION SHALL BE RUBBER STAMPED OR SILKSCREENED AT THE VENDORS DISCRETION ON EITHER SIDE OF THE BOARD
7. OTHER APPLICABLE STANDARDS:
 - A. FABRICATE PER IPC-2221B, CLASS 2 LEVEL B, IPC-2222 TYPE 3, INSPECT PER IPC-A-600J, CLASS 2
 - B. FABRICATE IN ACCORDANCE WITH IPC-6012D, CLASS 2, PER IPC-6011 USING SUPPLIED DATA FILES
 - C. THIS BOARD TO CONFORM TO UL94V-0
8. OTHER APPLICABLE NOTES:
 - A. REFER TO STACKUP INFORMATION
 - B. ALL NON-FUNCTIONAL PADS TO BE REMOVED
 - C. TEARDROPPING IS ACCEPTABLE ON SIGNAL LAYERS
 - D. COPPER THIEVING MAY BE ADDED AS REQUIRED
 - E. BOW OR TWIST NOT TO EXCEED 7 mil/in.
 - F. THE PCB SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. THE RESULTS OF THIS TEST SHALL BE DOCUMENTED AND DELIVERED WITH EACH LOT
9. ROHS COMPLIANCE IS REQUIRED
 - A. ALL MATERIALS USED WITHIN THE FABRICATION ARE TO BE ROHS COMPLIANT AND MUST SUPPORT A PB-FREE ASSEMBLY PROCESS (E.G. ACCEPTABLE TG/TD ETC)
10. ANY ARTWORK MODIFICATIONS MUST BE REVIEWED AND APPROVED BY LTL TEK PRIOR TO MANUFACTURING



LAYER STACKUP

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Epoxy	0.01 mm	Green	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In1.Cu	copper		0.035 mm		1	0
Dielectric 2	core	FR4	1.24 mm	Not specified	4.5	0.02
In2.Cu	copper		0.035 mm		1	0
Dielectric 3	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Epoxy	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

